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FORM PTO-1595 (modified)
(Rev. 8-93)

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OMB No. 0651-0011 (exp. 4/94)

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Jung-Ho LEE, Dong-Jun LEE, Dae-Won KANG, Sung-Taek MOON, Gi-Hag LEE, Jung-Sik CHOI

Additional name(s) of conveying party(ies) attached? No

11/05/01

2. Name and address of receiving party(ies):

Name: Samsung Electronics Co., Ltd.

Internal Address:

Street Address: 416 Maetan-dong, Paldal-gu,

City: Suwon-city, Kyungki-do, REPUBLIC OF KOREA

Additional name(s) & address(es) attached? No

11000 U.S. PTO
09/985615
11/05/01

3. Nature of conveyance

☒ Assignment Merger
Security Agreement Change of Name
Other

Execution Date:

4. Application number(s) or patent number(s):

09/985615

If this document is being filed together with a new application, the execution date of the application is: October 27, 2001

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Eugene M. Lee

Internal Address: THE LAW OFFICES OF EUGENE M. LEE
PLLC

Street Address: 2111 Wilson Boulevard, Suite 1200

City: Arlington, State: VA ZIP: 22201

6. Total number of applications and patents involved: One

7. Total fee (37 C.F.R. 3.41). \$40.00

☒ Enclosed
Authorized to be charged to deposit account

8. Deposit account number: 5-01645

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Eugene M. Lee

Richard A. Sterba

Name of Person Signing



Signature

November 5, 2001

Date

Total number of pages including cover sheet, attachmets, and document: 2 pages attached, incl. cover

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks, Box Assignments

Washington, D.C. 20231

PATENT
REEL: 012299 FRAME: 0626

ASSIGNMENT

name and address of assignee	For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each undersigned inventor has sold and assigned, and by these presents hereby sells and assigns, unto
	SAMSUNG ELECTRONICS CO., LTD. 416 Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea
	(hereinafter ASSIGNEE) all right, title and interest for the United States, its territories and possessions in and to his invention relating to

title of invention	METHOD OF FORMING SILICON OXIDE LAYER IN SEMICONDUCTOR MANUFACTURING PROCESS USING SPIN-ON GLASS COMPOSITION AND ISOLATION METHOD USING THE SAME METHOD
	as set forth in this United States Patent Application

check one	<input checked="" type="checkbox"/> executed concurrently herewith
	executed on <u>10/27/01</u>
	Serial No. _____ Filed _____

in and to said United States Patent Application including any and all divisions or continuations thereof and in and to any and all Letters Patent of the United States which may issue on any such application or for said invention, including any and all reissues or extensions thereof, to be held and enjoyed by said ASSIGNEE, its successors, legal representatives and assigns to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made;

Each of the undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent to said ASSIGNEE, its successors or assigns in accordance herewith;

Each of the undersigned warrants and covenants that he has the full and unencumbered right to sell and assign the interests herein sold and assigned and that he has not executed and will not execute any document or instrument in conflict herewith;

Each of the undersigned further covenants and agrees he will communicate to said ASSIGNEE, its successors, legal representatives or assigns all information known to him relating to said invention or patent application and that he will execute and deliver any papers, make all rightful oaths, testify in any legal proceedings and perform all other lawful acts deemed necessary or desirable by said ASSIGNEE, its successors, legal representatives or assigns to perfect title to said invention, to said application including divisions and continuations thereof and to any and all Letters Patent which may be granted therefor or thereon, including reissues or extensions, in said ASSIGNEE, its successors, or assigns or to assist said ASSIGNEE, its successors, legal representatives or assigns in obtaining, reissuing or enforcing Letters Patent of the United States for said invention;

Each of the undersigned hereby grants the firm of **The Law Offices of Eugene M Lee, PLLC** the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

NAMES AND SIGNATURES OF INVENTORS		
Name: Jung-Ho LEE	Signature: <i>Jung-Ho Lee</i>	Date: <u>10/27/01</u>
Name: Dong-Jun LEE	Signature: <i>Dong-Jun Lee</i>	Date: <u>10/27/01</u>
Name: Dae-Won KANG	Signature: <i>Dae-Won Kang</i>	Date: <u>10/27/01</u>
Name: Sung-Taek MOON	Signature: <i>Sung-Taek Moon</i>	Date: <u>10/27/01</u>
Name: Gi-Hag LEE	Signature: <i>Gi-Hag Lee</i>	Date: <u>10/27/01</u>
Name: Jung-Sik CHOI	Signature: <i>Jung-Sik Choi</i>	Date: <u>10/27/01</u>
NAMES AND SIGNATURES OF WITNESSES		
Name:	Signature:	Date:
Name:	Signature:	Date:

Note: *Prima facie* evidence of execution may optionally be obtained by execution of this document before a U.S. Consul or before a local officer authorized to administer oaths whose authority is proved by a certificate from a U.S. Consul.